



Material Declaration Data Sheet

Product: Intel Server System SR9000MK4U

Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes noted on Page 2

Lead Free (Pb) Product: **NO**

Date: February 8, 2008

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

- 1. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- 2. Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 3. Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 4. Lead as an alloying element in copper containing up to 4 % lead by weight.
- 5. Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 6. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7. Lead in electronic ceramic parts (e.g. piezoelectric devices).
- 8. Lead used in compliant pin connector systems.
- 9. Lead as a coating material for the thermal conduction module c-ring.
- 10. Lead in optical and filter glass.
- 11. Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- 12. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 13. Cadmium in optical and filter glass.
- 14. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- 15. Lead in bronze bearing shells and brushes.
- 16. Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

Product Code Information



Product Code	Description	*RoHS Exemption #
SR9000MK4U	Four way Dual-Core Itanium® 2 4U server	6, 12
A9000MKMEM	SR9000MK4U Memory Riser Box	6
A9000MKHDC	SR9000MK4U HDD carrier	None
A9000KVMCD	SR9000MK4U KVM card	None
A9000CBARM	SR9000MK4U Cable Arm Kit	None
A9000RAILS	SR9000MK4U Rail Kit	None
A9000MKSAS	SR9000MK4U SAS Cable	None
F9000MKBRD	SR9000MK4U Server Board	6, 12
F9000MKPSU	SR9000MK4U Power Supply	None
F9000MKFAN	SR9000MK4U Cooling Fan	None
F9000OPPNL	SR9000MK4U Front Panel	6
F9000OPCBL	SR9000MK4U Front Panel Cable	None
F9000OPPCB	SR9000MK4U Front Panel Power Cord	None
F9000MKHBP	SR9000MK4U HDD Backplane	None
F9000MVRCB	SR9000MK4U MVR Y-Cable	None
F9000DVFIX	SR9000MK4U DVD-Drive Fixing Hook	None
F9000MKBZL	SR9000MK4U Front Bezel	None
A9000HSINK	SR9000MK4U Heatsink	6

* RoHS Exemption # corresponds with exemption #'s found on page 1.